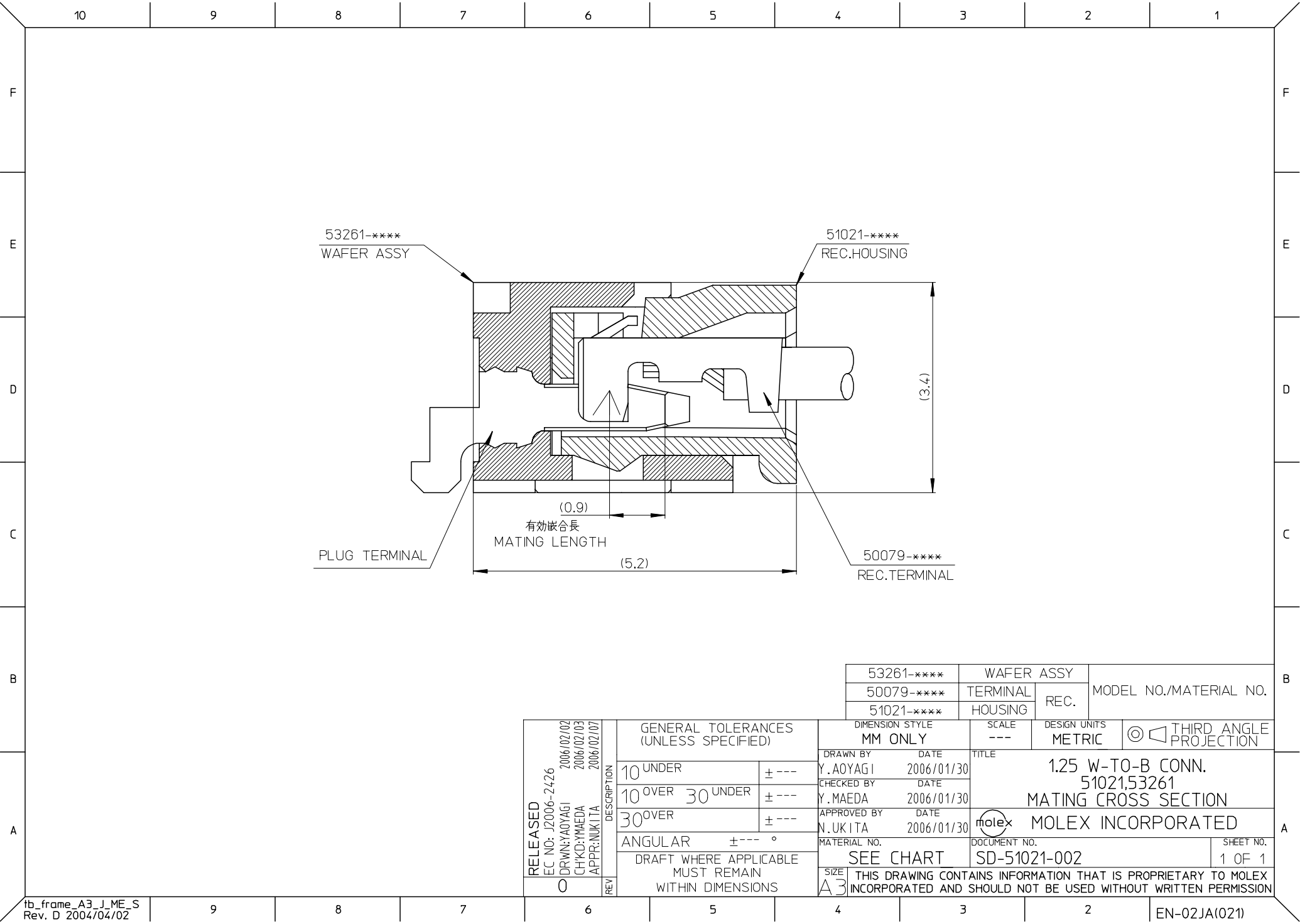
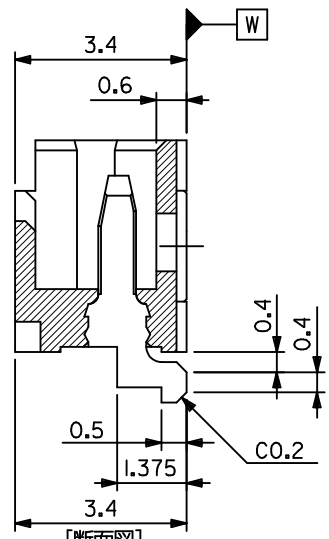
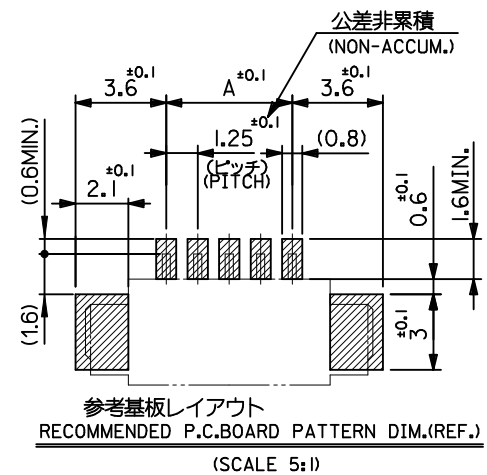
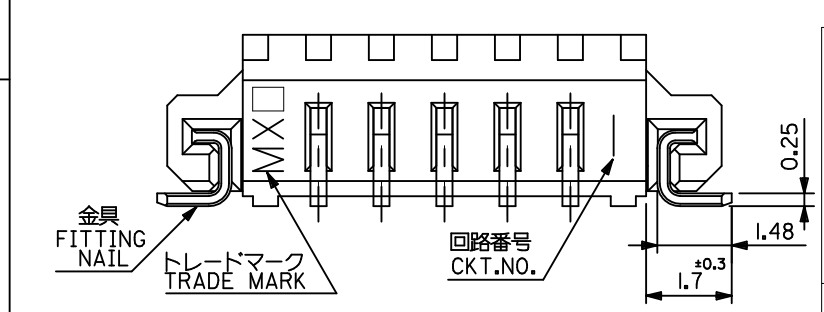
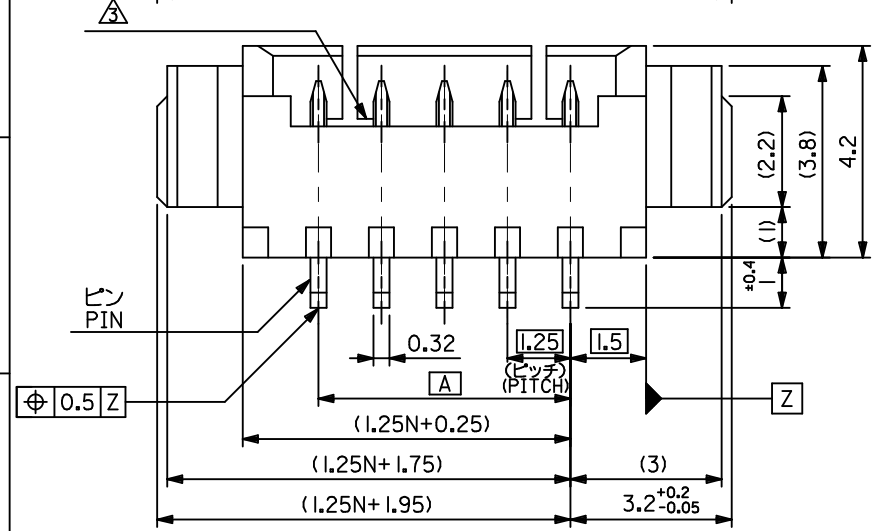
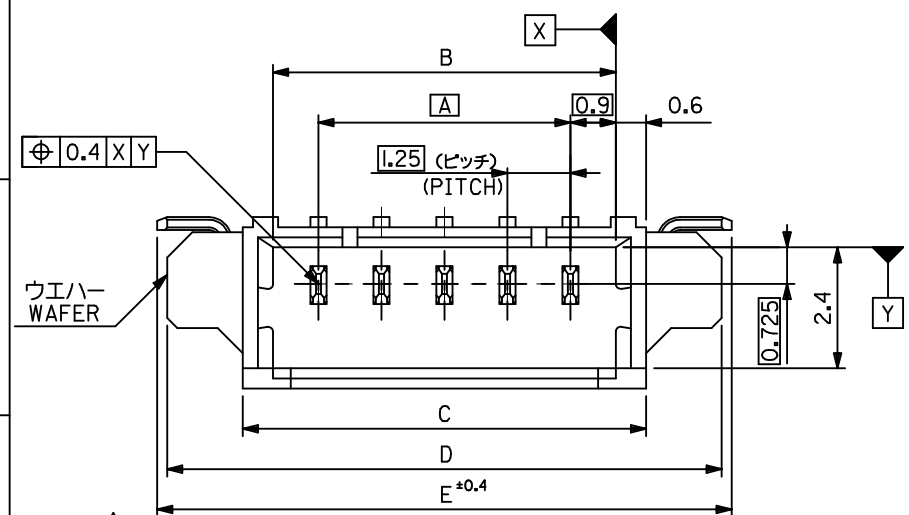




53261-****	WAFER ASSY	MODEL NO./MATERIAL NO.
50079-****	TERMINAL	
51021-****	HOUSING	

RELEASED EC NO: J2006-2426 DRWN: YAOYAGI 2006/02/02 CHKD: YMAEDA 2006/02/03 APPR: NUKITA 2006/02/07 REV 0	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± ---	DRAWN BY Y. AOYAGI	DATE 2006/01/30	TITLE 1.25 W-TO-B CONN. 51021,53261 MATING CROSS SECTION				
		10 OVER 30 UNDER	± ---	CHECKED BY Y. MAEDA	DATE 2006/01/30					
		30 OVER	± ---	APPROVED BY N. UKITA	DATE 2006/01/30	MOLEX INCORPORATED				
		ANGULAR ± --- °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-51021-002		1 OF 1			
				SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				



[断面図]

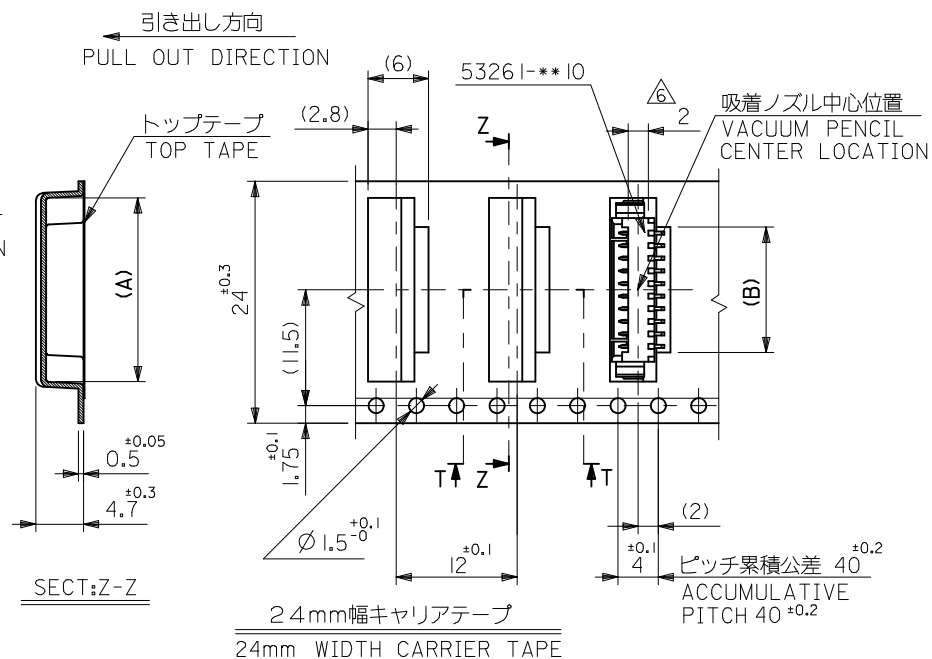
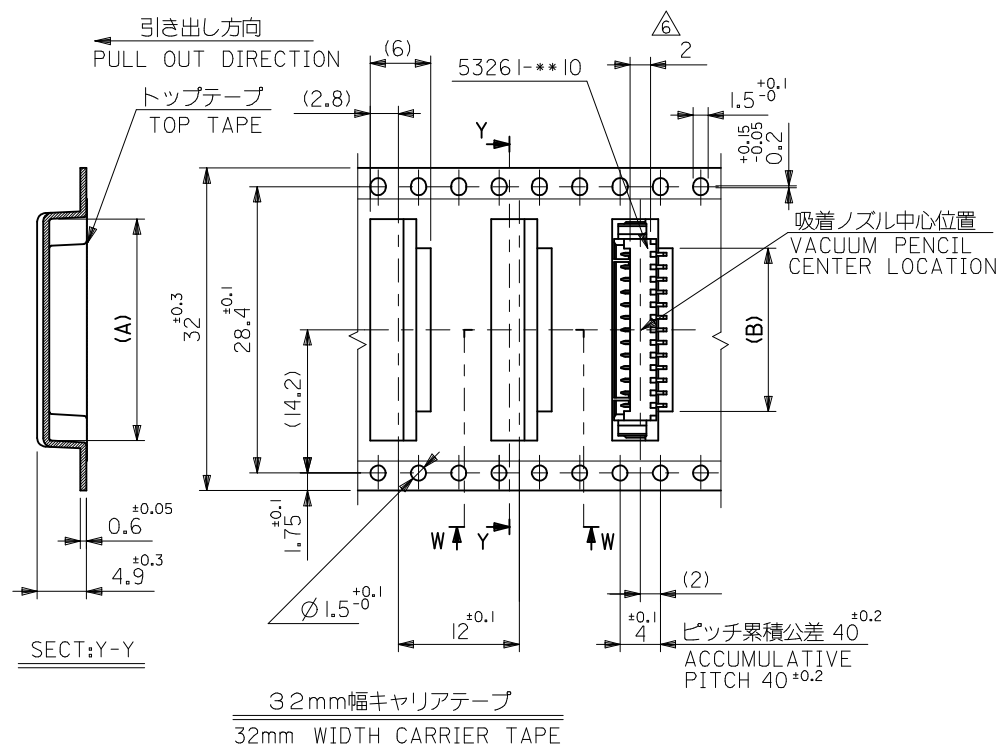
[CROSS SECTION]

注記 NOTES

1. 嵌合相手: 51021 シリウス
MATES WITH: 51021 SERIES
2. 材質 MATERIAL
ウエハー: NYLON46, UL94V-0
ピン: リン青銅, 半田メッキ
PIN: PHOS-BRO., Sn-Pb(9:1) 3 μmMIN.
OVER Cu 1 μmMIN.
PLATING
金具: リン青銅, 半田メッキ
FITTING NAIL: PHOS-BRO., Sn-Pb(9:1) 2 μmMIN.
OVER Cu 1 μmMIN.
PLATING
3. ロック窓は2、3極は1箇所、4極以上は2箇所とする。
LOCKING WINDOW: ONE PLACE FOR 2 AND 3 CKT. AND TWO PLACES FOR MORE THAN 3 CKT.
4. ソルダータール部のズレ量及び金具 (補強板) のズレ量は基準面 W に対し、上方向 0.05 MAX.、下方向に 0.1 MAX. とする。
OFFSET BETWEEN BASIS PLANE W TO SOLDER TAIL BOTTOM AND FITTING NAIL BOTTOM: UPPER SIDE: 0.05MAX. LOWER SIDE: 0.1MAX.

23.9	23.5	20.5	19.3	17.5	53261-1510	15
22.65	22.25	19.25	18.05	16.25	-1410	14
21.4	21	18	16.8	15	-1310	13
20.15	19.75	16.75	15.55	13.75	-1210	12
18.9	18.5	15.5	14.3	12.5	-1110	11
17.65	17.25	14.25	13.05	11.25	-1010	10
16.4	16	13	11.8	10	-0910	9
15.15	14.75	11.75	10.55	8.75	-0810	8
13.9	13.5	10.5	9.3	7.5	-0710	7
12.65	12.25	9.25	8.05	6.25	-0610	6
11.4	11	8	6.8	5	-0510	5
10.15	9.75	6.75	5.55	3.75	-0410	4
8.9	8.5	5.5	4.3	2.5	-0310	3
7.65	7.25	4.25	3.05	1.25	53261-0210	2
E	D	C	B	A	ENG. NO.	極数 CKT.

REVISED EC NO: J2012-1315 2012/04/17 DRWN: NITO CHKD: KASAKAWA 2012/04/17 APPR: YOITO 2012/04/26	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1		DESIGN UNITS METRIC		THIRD ANGLE PROJECTION	
		10 UNDER ±0.2		DRAWN BY NITO		DATE 2012/04/17		TITLE 1.25 WIRE TO BOARD WAFER ASS FOR SMT RIGHT ANGLE molex SD-53261-054			
		10 OVER 30 UNDER ±0.25		CHECKED BY KASAKAWA		DATE 2012/04/17					
		30 OVER ±0.3		APPROVED BY YOITO		DATE 2012/04/26					
		ANGULAR ±3 °		MATERIAL NO. SEE DRAWING		DOCUMENT NO. SD-53261-054		SHEET NO. 1 OF 1			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							



32	32.4	16.2	22	53261-1390	13
		14.95	20.75	-1290	12
		13.7	19.5	-1190	11
24	24.4	12.45	18.25	-1090	10
		11.2	17	-0990	9
		9.95	15.75	-0890	8
		8.7	14.5	-0790	7
		6.2	12	-0590	5
		4.95	10.75	53261-0490	4
キャリアテープ幅 CARRIER TAPE WIDTH	C	B	A	ENG. NO.	種数 CKT.

REVISED EC NO: J2014-1616 DRWN: TYAJI MA01 CHKD: KASAKAWA APPR: NUKITA	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± ---	TYAJI MA01	2014/04/28	TITLE 1.25 W/B CONN. WAFER ASSY FOR SMT. EMBOSSED TAPE PACKAGE				
		10 OVER 30 UNDER	± ---	CHECKED BY KASAKAWA	2014/04/28					
		30 OVER	± ---	APPROVED BY NUKITA	2014/04/30	molex				
		ANGULAR ± --- °		MATERIAL NO.						
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE NOTES		SD-53261-055			2 OF 3		
	REV			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[Molex:](#)

[53261-1590](#)